COATED SOLDER PASTE STENCIL AND THE METHOD OF PRODUCING THEREOF

ABSTRACT

Embodiments of the present invention relate to the field of electronics manufacturing or surface mount technology (SMT) and, more specifically, to solder paste stencils (1) with coatings on at least one of its surfaces (3a, 3b) and aperture wall (51), as well as a manufacturing method (100) for producing them. The invention introduces a coating process with specialized materials, aimed at preventing solder paste adherence and enhancing hydrophobicity. The resulting coated solder paste stencil (1) exhibits improved solder paste flow, reduced clogging, and ensures precise deposition, enhance solder paste release capability, marking a significant advancement in electronics manufacturing.

(The most illustrative figure is FIG. 1-A)